



Material Content Data Sheet



Sales Product Name	BAR 64-06W H6327			Issued		29. August 2013		
MA#	MA000856190							
Package	PG-SOT323-3-1			Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		12	
	noble metal	gold	7440-57-5	0.007	0.12		1153	
	inorganic material	silicon	7440-21-3	0.059	0.98	1.10	9845	11010
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.89	44.07	438796	440647
wire	non noble metal	copper	7440-50-8	0.004	0.07	0.07	702	702
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5237	
	plastics	epoxy resin	-	0.672	11.26		112598	
	inorganic material	silicondioxide	60676-86-0	2.421	40.59	52.37	405877	523712
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22250	22250
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1679	1679
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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